



Metallization of Non-Conductive Substrates

Guest Editor:

Prof. Dr. Chih-Ming Chen

Department of Chemical
Engineering, National Chung
Hsing University, Taichung 402,
Taiwan

Deadline for manuscript
submissions:

closed (31 December 2017)

Message from the Guest Editor

Dear Colleagues,

This Special Issue aims to highlight recent advancement in the science and technology associated with metallization of non-conductive substrates. Metallization of non-conductive substrates plays an important role in various application fields including microelectronics and optoelectronics. In some specific applications, such as flexible electronics, metallization of polymeric substrates especially attracts more attention. Vacuum-based deposition method can grow a uniform and adhesive metal or alloy film on non-conductive substrates but expensive facilities are always a big concern. Solution-based deposition method is rather simple and cost-effective but an improvement of the film uniformity and adhesion requires more research works. In this special issue, substrates of interests include, but are not limited to, polymer, glass, ceramic, and silicon. Specific topic areas for manuscript submissions include, but are not limited to, methodology of physical and chemical deposition, structures and properties of deposits, new catalysts and deposition methods, metals and alloys deposition, and adhesion and interfacial properties.





an Open Access Journal by MDPI

Editors-in-Chief

Prof. Dr. Hugo F. Lopez

Department of Materials Science
and Engineering, College of
Engineering & Applied Science,
University of Wisconsin-
Milwaukee, 3200 N. Cramer
Street, Milwaukee, WI 53211, USA

Prof. Dr. Yong Zhang

Beijing Advanced Innovation
Center of Materials Genome
Engineering, State Key
Laboratory for Advanced Metals
and Materials, University of
Science and Technology Beijing,
30 Xueyuan Road, Beijing 100083,
China

Message from the Editorial Board

Metallic materials play a vital role in the economic life of modern societies; contributions are sought on fresh developments that enhance our understanding of the fundamental aspects related to the relationships between processing, properties and microstructure – disciplines in the metallurgical field ranging from processing, mechanical behavior, phase transitions and microstructural evolution, nanostructures, as well as unique metallic properties – inspire general and scholarly interest among the scientific community.

Author Benefits

Open Access: free for readers, with **article processing charges (APC)** paid by authors or their institutions.

High Visibility: indexed within **Scopus**, **SCIE (Web of Science)**, **Inspec**, **CAPLUS / SciFinder**, and **other databases**.

Journal Rank: JCR - Q2 (*Metallurgy & Metallurgical Engineering*) / CiteScore - Q1 (*Metals and Alloys*)

Contact Us

Metals Editorial Office
MDPI, St. Alban-Anlage 26
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/metals
metals@mdpi.com
[X@Metals_MDPI](https://twitter.com/X@Metals_MDPI)